

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

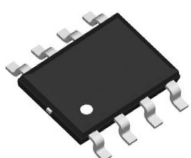
Product Summary



V_{DS}	150	V
I_D	5.2	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	44	m Ω

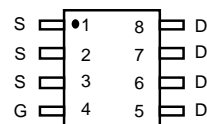
Applications

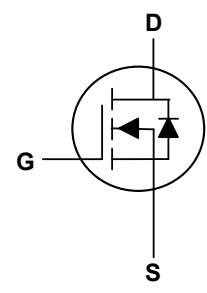
- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



SOP-8 Top View

Top View





Absolute Maximum Ratings($T_A=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D@T_C=25^{\circ}C$	5.2	A
Continuous Drain Current	$I_D@T_C=100^{\circ}C$	3.7	A
Pulsed Drain Current ¹	I_{DM}	42	A
Total Power Dissipation	P_D	3.5	W
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	35.7	$^{\circ}C/W$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	150	170	---	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5.2A$	---	31	44	m Ω
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.5	3.2	4.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=150V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=50V, I_D=5.2A$	12	--	---	S
Total Gate Charge	Q_g	$V_{DS}=75V, V_{GS}=10V, I_D=3.1A$	---	35.8	---	nC
Gate-Source Charge	Q_{gs}		---	7.5	---	
Gate-Drain Charge	Q_{gd}		---	13	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=75V, I_D=3.1A, V_{GS}=10V, R_G=6.5\Omega$	---	15	---	ns
Rise Time	T_r		---	13	---	
Turn-Off Delay Time	$T_{d(off)}$		---	26	---	
Fall Time	T_f		---	14	---	
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	1700	---	pF
Output Capacitance	C_{oss}		---	190	---	
Reverse Transfer Capacitance	C_{rss}		---	90	---	

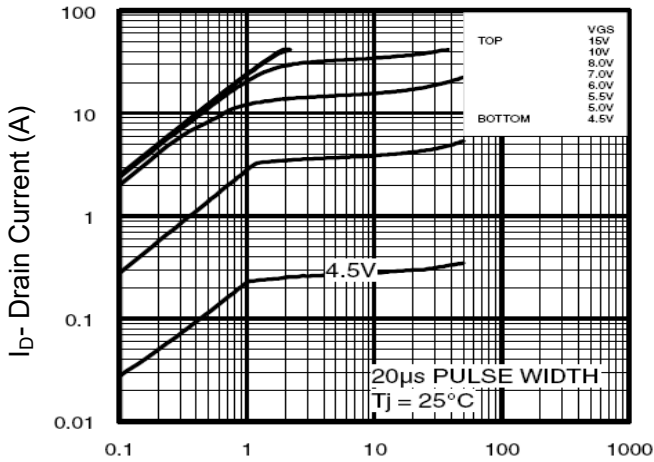
Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ¹	I_S		---	---	2.7	A
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=3.1A, T_J=25^{\circ}\text{C}$	---	---	1.2	V
Reverse Recovery Time	t_{rr}	$I_F=3.1A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	50	---	nS
Reverse Recovery Charge	Q_{rr}		---	140	---	nC

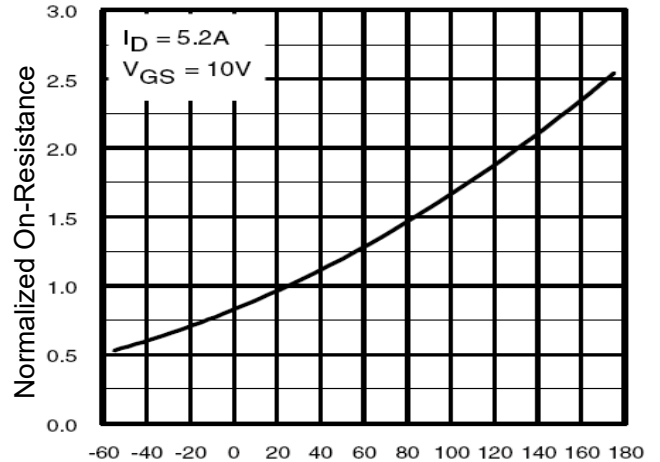
Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature

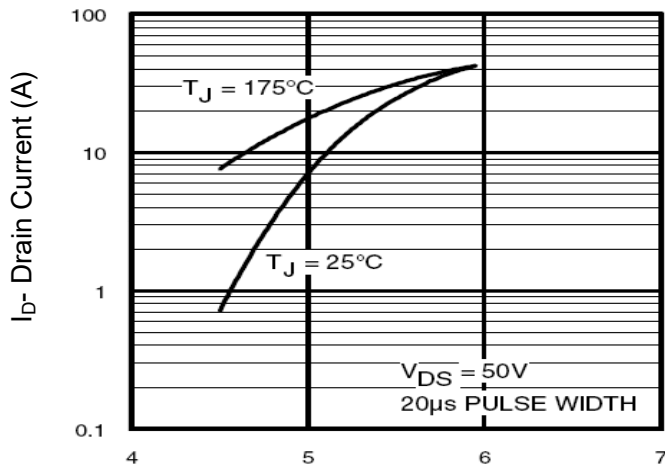
Typical Characteristics



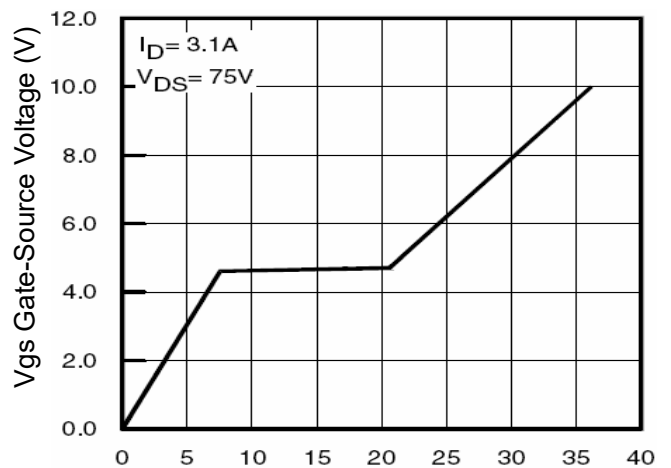
Vds Drain-Source Voltage (V)
Figure 1 Output Characteristics



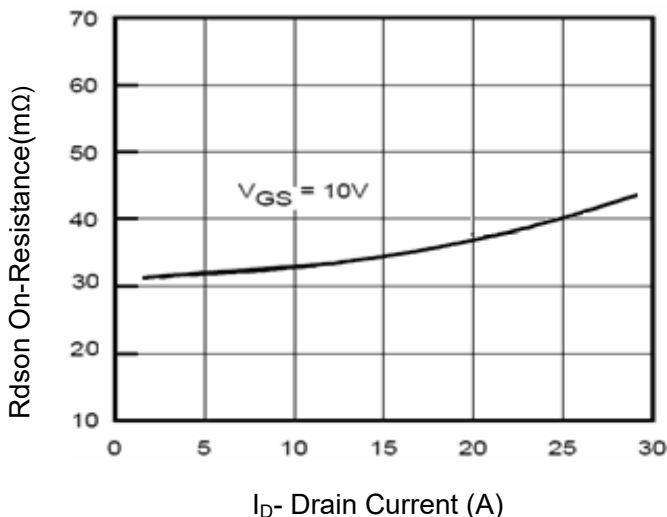
Tj-Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature



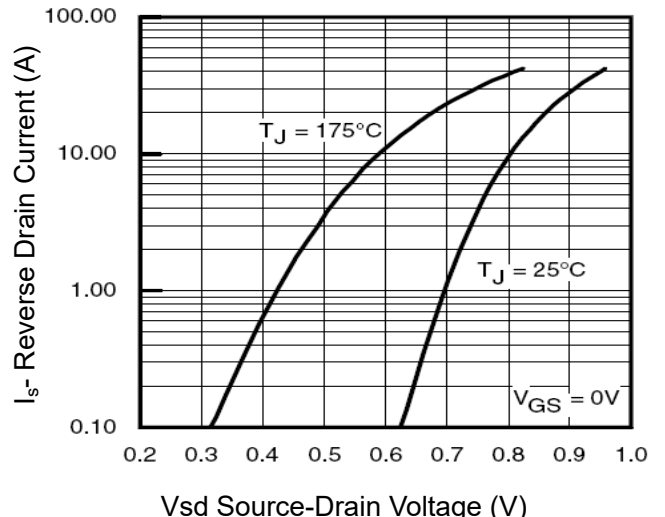
Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge



Id- Drain Current (A)
Figure 3 Rdson- Drain Current



Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward

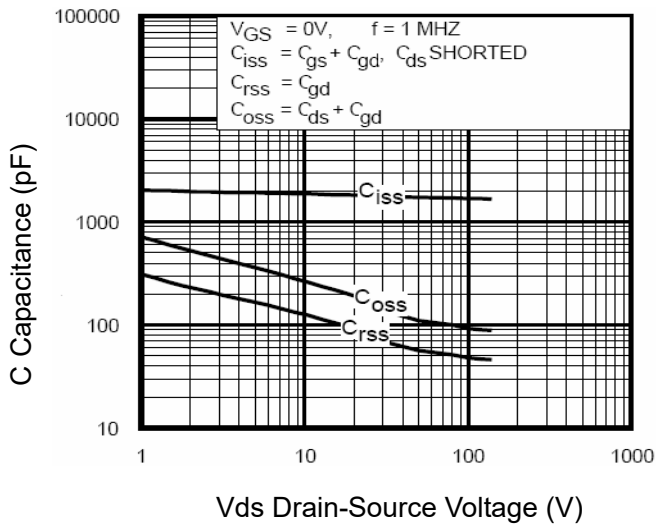


Figure 7 Capacitance vs Vds

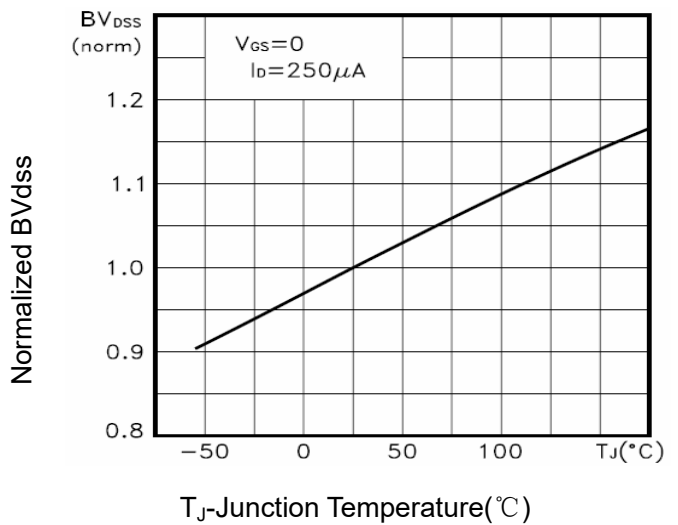


Figure 9 BV_{DSS} vs Junction Temperature

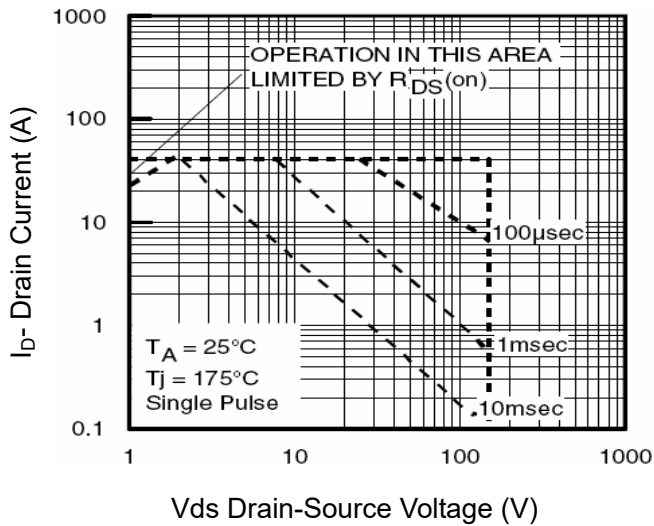


Figure 8 Safe Operation Area

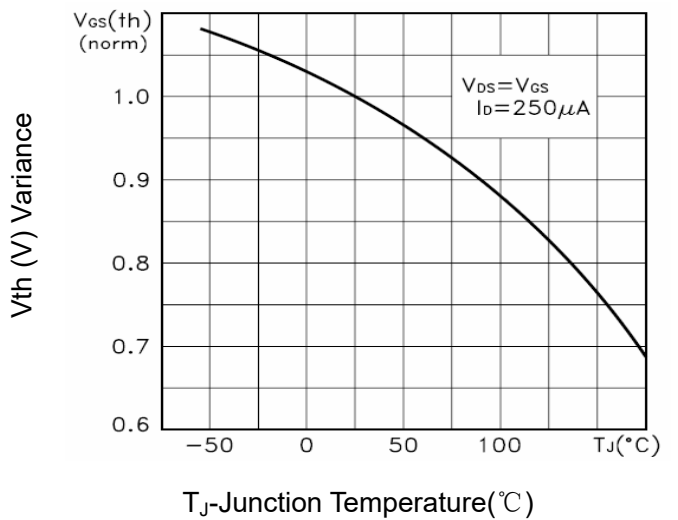


Figure 10 $V_{GS(th)}$ vs Junction Temperature

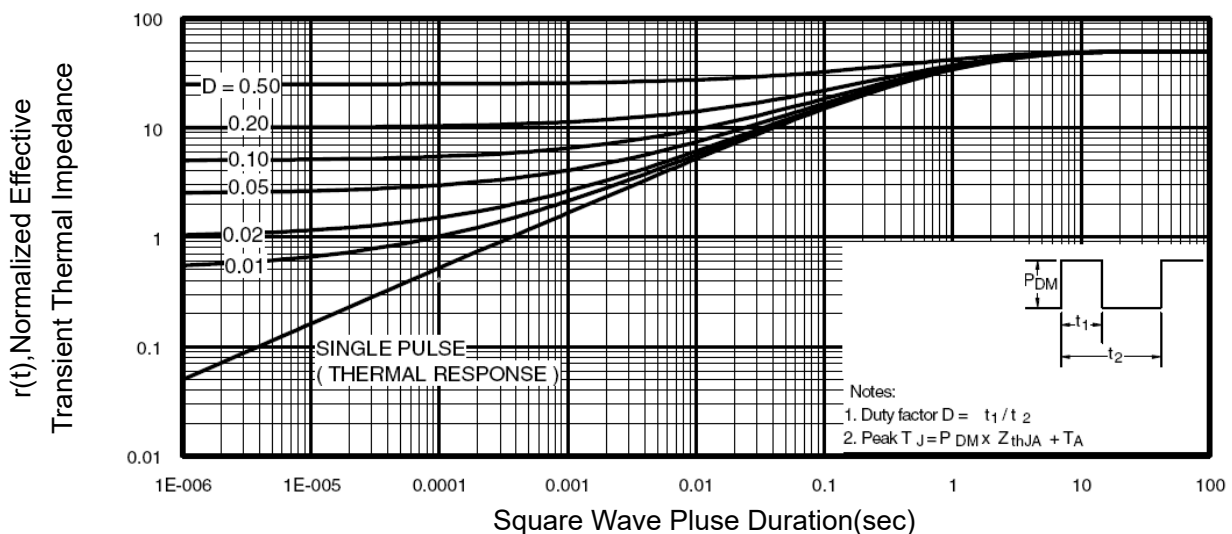
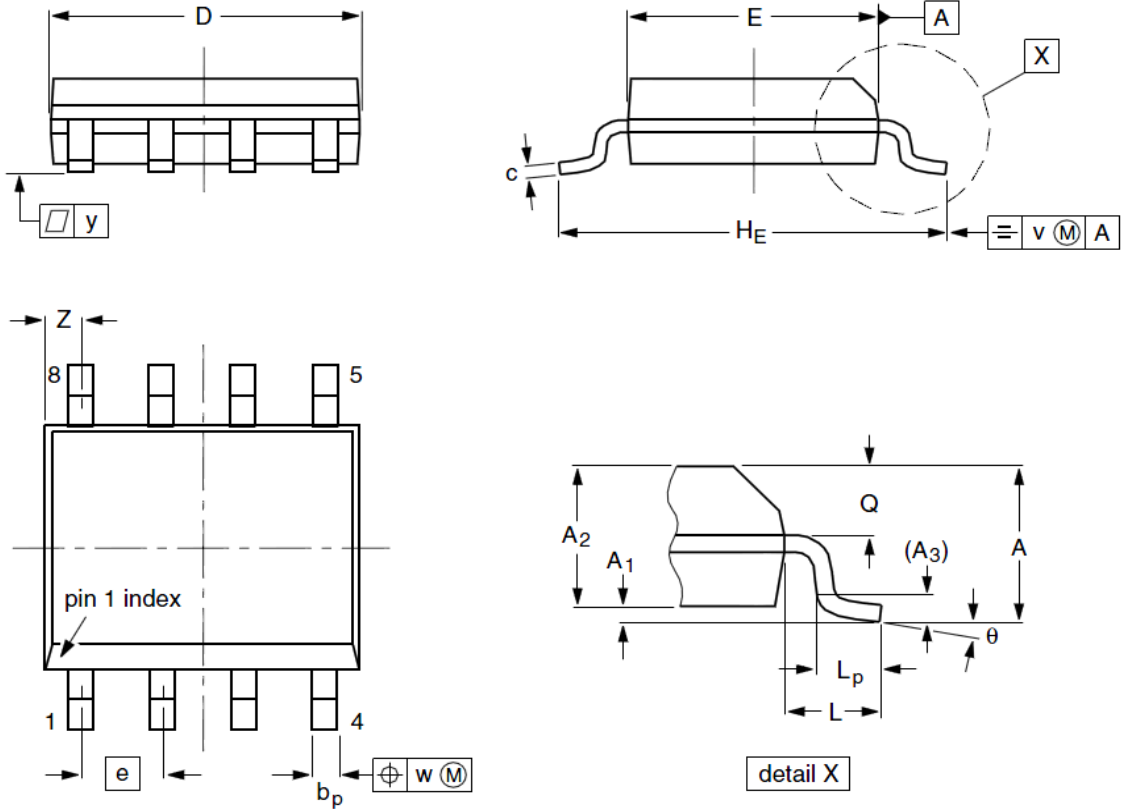


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	1.35	1.55	1.75	A₁	0.10	0.18	0.25
A₂	1.25	1.45	1.65	A₃	--	0.25	--
b_p	0.36	0.42	0.51	c	0.19	0.22	0.25
D	4.70	4.92	5.10	E	3.80	3.90	4.00
e	--	1.27	--	H_E	5.80	6.00	6.20
L	--	1.05	--	L_p	0.40	0.68	1.00
Q	0.60	0.65	0.73	v	--	0.25	--
w	--	0.25	--	y	--	0.10	--
Z	0.30	0.50	0.70	θ	0°		8°